



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	RDS(ON) max	Package	I _D T _A = +25°C
-25V	27mΩ @ V _{GS} = -4.5V	U-DFN2020-6	-6.7A
-25V	40mΩ @ V _{GS} = -1.8V	(Type E)	-5.4A

Description

This new generation MOSFET has been designed to minimize the onstate resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switching
- Battery Management Application
- Power Management Functions

Features

- Low R_{DS(ON)} Ensures on State Losses are Minimized
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- ESD Protected Gate
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

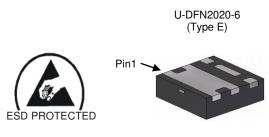
https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

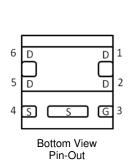
https://www.diodes.com/quality/product-definitions/

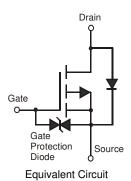
Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3
- Weight: 0.001 grams (Approximate)









Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2039UFDE-7	U-DFN2020-6 (Type E)	3,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



P9 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Date Code Ney												
Year	2011		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Υ		Н		J	K	L	М	N	0	Р	R
									_			
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	0	0	4		_	7	0			N.I.	

Site 2



P9 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2011		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	1		0	1	2	3	4	5	6	7	8	9
Week	1-26				27-	-52		53				
Code		Α	-Z			a	-Z			7	Z	
Internal Code	Sur	1	Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		U		V	V	٧	Х		Υ		Z



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	-25	V		
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note EVV 4 EV	Steady State	T _A = +25°C T _A = +70°C	lD	-6.7 -5.3	А
Continuous Drain Current (Note 5) V _{GS} = -4.5V	t<5s	T _A = +25°C T _A = +70°C	lD	-8.3 -6.6	А
Continuous Dusin Courset (Nata 5) V 4 0V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	l _D	-5.4 -4.3	А
Continuous Drain Current (Note 5) V _{GS} = -1.8V	t<5s	T _A = +25°C T _A = +70°C	I _D	-6.6 -5.2	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	-60	Α		
Continuous Source-Drain Diode Current	Is	-2.0	Α		

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C	D-	0.8	W
Total Fower Dissipation (Note 5)	$T_A = +70^{\circ}C$	P _D	1.2	VV
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	160	°C/W
Thermal Resistance, Junction to Ambient (Note 3)	t<5s	RθJA	104	C/ VV
Total Bower Dissipation (Note 6)	$T_A = +25$ °C	Pn	2.0	w
Total Power Dissipation (Note 6)	T _A = +70°C	PD	2.9	VV
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	63	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<5s	RθJA	42	C/VV
Thermal Resistance, Junction to Case (Note 6)	Steady State	Rejc	10.8	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)			•		•	
Drain-Source Breakdown Voltage	BV _{DSS}	-25	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -25V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±10	μΑ	$V_{GS} = \pm 8.0V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	_	-1.0	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
			20	27		$V_{GS} = -4.5V$, $I_{D} = -6.4A$
Static Drain-Source On-Resistance	Pro/out		24	34	mΩ	$V_{GS} = -2.5V, I_D = -4.8A$
Static Diam-Source Off-Nesistance	Rds(on)		28	40	11152	$V_{GS} = -1.8V, I_{D} = -2.5A$
			33	70		$V_{GS} = -1.5V, I_{D} = -1.5A$
Forward Transfer Admittance	Y _{fs}		16	_	S	$V_{DS} = -5V, I_{D} = -4A$
Diode Forward Voltage	V _{SD}		-0.7	-1.0	V	$V_{GS} = 0V$, $I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	2530	_	pF	V 15V V 0V
Output Capacitance	Coss		203	_	pF	V _{DS} = -15V, V _{GS} = 0V -f = 1.0MHz
Reverse Transfer Capacitance	Crss		177	_	pF	1 = 1.0WHZ
Gate Resistance	R_g		9.1	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg	1	28.2	_	nC	
Total Gate Charge (VGS = -8V	Qg		48.7	_	nC	V 15V I- 10A
Gate-Source Charge	Qgs	_	3.2	_	nC	$V_{DS} = -15V, I_{D} = -4.0A$
Gate-Drain Charge	Qgd		5.0	_	nC	
Turn-On Delay Time	td(ON)		15.1	_	ns	
Turn-On Rise Time	tR		23.5	_	ns	$V_{DD} = -15V$, $V_{GS} = -4.5V$, $R_{G} = 1\Omega$,
Turn-Off Delay Time	tD(OFF)		137.6	_	ns	I _D = -4.0A
Turn-Off Fall Time	t _F	1	80.5	_	ns	

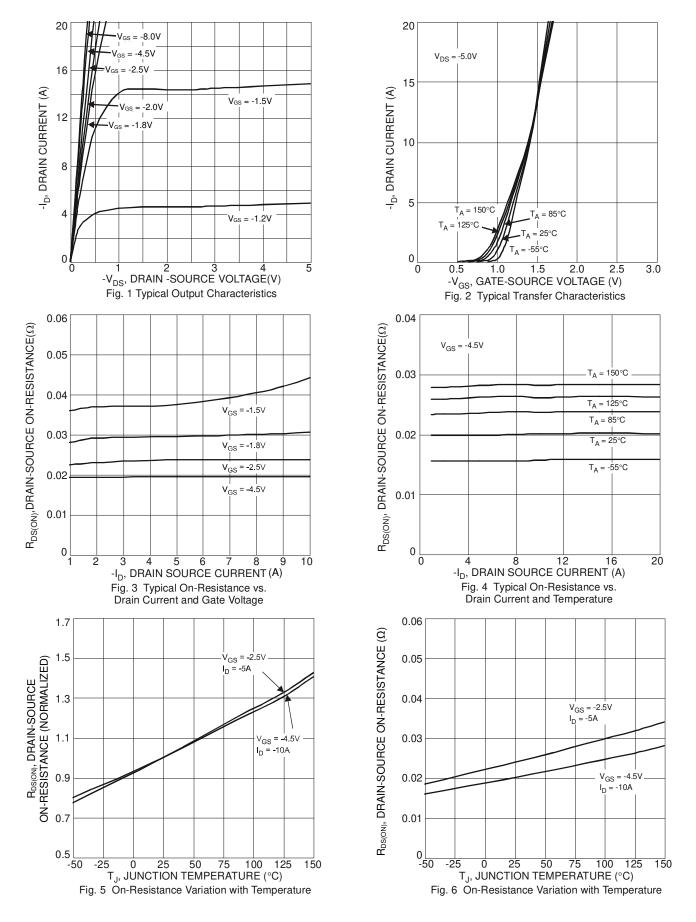
Notes:

^{5.} Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to production testing.







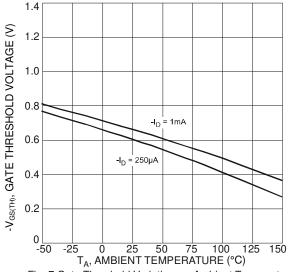
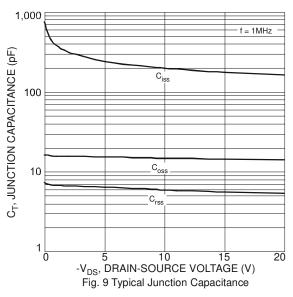
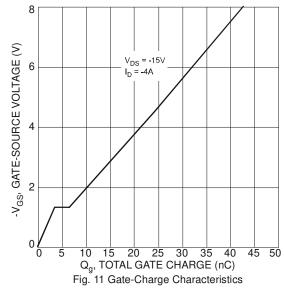
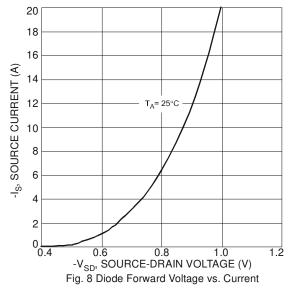


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







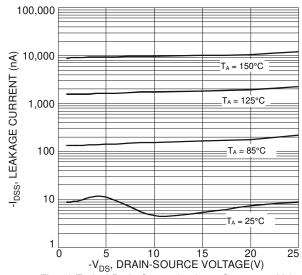
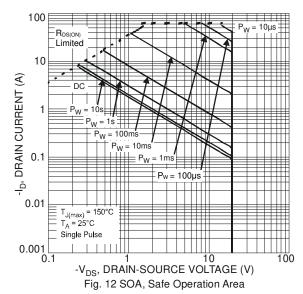


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage





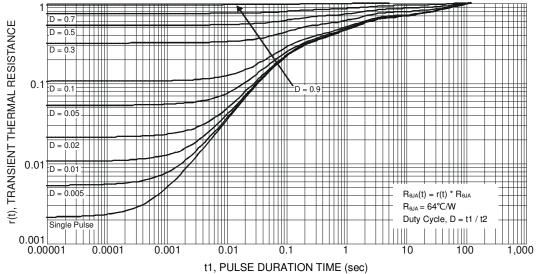


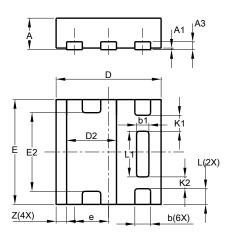
Fig. 13 Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type E)

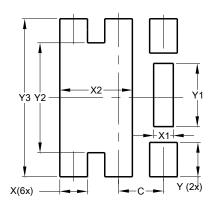


	U-DFN2020-6 Type E								
Dim	Min Max Typ								
Α	0.57	0.63	0.60						
A1	0	0.05	0.03						
A3	_	1	0.15						
b	0.25	0.35	0.30						
b1	0.185	0.285	0.235						
D	1.95	2.05	2.00						
D2	0.85	1.05	0.95						
E	1.95	2.05	2.00						
E2	1.40	1.60	1.50						
е	_	-	0.65						
L	0.25	0.35	0.30						
L1	0.82	0.92	0.87						
K1			0.305						
K2	_	_	0.225						
Z	_	_	0.20						
All	Dimen	sions i	in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type E)



Dimensions	value
Dillielisions	(in mm)
С	0.650
X	0.400
X1	0.285
X2	1.050
Υ	0.500
Y1	0.920
Y2	1.600
Y3	2.300



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